

TENTATIVE

TPCP8001-H

High Speed and High Efficiency DC-DC Converters

Notebook PC Applications

Portable Equipment Applications

- Small footprint due to small and thin package
- High speed switching
- Small gate charge: $Q_{sw} = 11 \text{ nC (typ.)}$
- Low drain-source ON resistance: $R_{DS(ON)} = 13 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 16 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 10 \mu\text{A (max)}$ ($V_{DS} = 30\text{V}$)
- Enhancement mode: $V_{th} = 1.1 \text{ to } 2.3 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

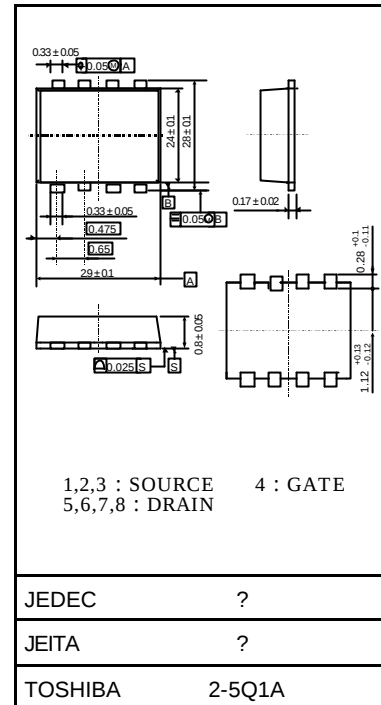
Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	30	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	30	V
Gate-source voltage		V_{GSS}	± 20	V
Drain current	DC (Note 1)	I_D	7.2	A
	Pulsed (Note 1)	I_{DP}	28.8	
Drain power dissipation ($t = 5 \text{ s}$) (Note 2a)		P_D	1.68	W
Drain power dissipation ($t = 5 \text{ s}$) (Note 2b)		P_D	0.84	W
Single pulse avalanche energy (Note 3)		E_{AS}	33.6	mJ
Avalanche current		I_{AR}	7.2	A
Repetitive avalanche energy ($T_c = 25^\circ\text{C}$) (Note 4)		E_{AR}	0.168	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	-55 to 150	$^\circ\text{C}$

Note: For (Note 1), (Note 2), (Note 3), (Note 4), please refer to the next page.

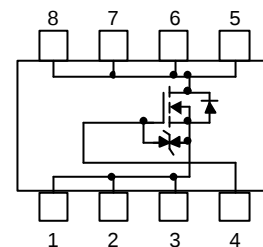
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm



Weight: 0.080 g (typ.)

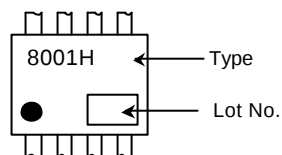
Circuit Configuration



Thermal Characteristics

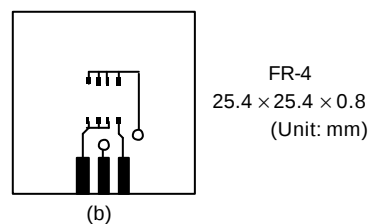
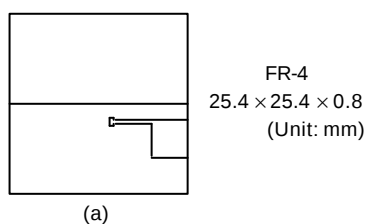
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	$R_{th (ch-a)}$	74.4	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	$R_{th (ch-a)}$	148.8	°C/W

Marking (Note 5)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

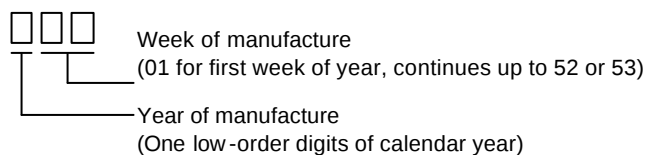
Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



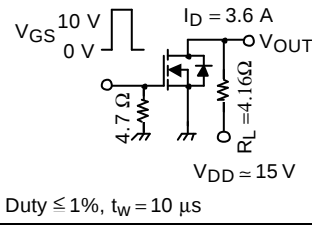
Note 3: $V_{DD} = 24 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.5 \text{ mH}$, $R_G = 1 \Omega$, $I_{AR} = 7.2 \text{ A}$

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: * Weekly code: (Three digits)



Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	—	—	±10	μA
Drain cut-OFF current		I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	—	—	10	μA
Drain-source breakdown voltage		V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	30	—	—	V
		V (BR) DSX	I _D = 10 mA, V _{GS} = −20 V	15	—	—	
Gate threshold voltage		V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.1	—	2.3	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4.5 V, I _D = 3.6 A	—	19	25	mΩ
			V _{GS} = 10 V, I _D = 3.6 A	—	13	16	
Forward transfer admittance		Y _{fs}	V _{DS} = 10 V, I _D = 3.6 A	10	19	—	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	—	640	—	pF
Reverse transfer capacitance		C _{rss}		—	75	—	
Output capacitance		C _{oss}		—	300	—	
Switching time	Rise time	t _r	 V_{GS} 10 V 0 V I_D = 3.6 A V_{OUT} 4.7 Ω R_L = 4.16Ω V_{DD} ≈ 15 V Duty ≤ 1%, t_w = 10 μs	—	4	—	ns
	Turn-ON time	t _{on}		—	8	—	
	Fall time	t _f		—	4	—	
	Turn-OFF time	t _{off}		—	18	—	
Total gate charge (gate-source plus gate-drain)		Q _g	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 7.2 A	—	11	—	nC
			V _{DD} ≈ 24 V, V _{GS} = 5 V, I _D = 7.2 A	—	6.3	—	
Gate-source charge 1		Q _{gs1}	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 7.2 A	—	2.2	—	
Gate-drain ("miller") charge		Q _{gd}		—	2.6	—	
Gate switch charge		Q _{sw}		—	3.6	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	I_{DRP}	—	—	—	28.8	A
Forward voltage (diode)		V_{DSF}	$I_{DR} = 7.2 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.2	V

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